

FP1008R7

High frequency, high current power inductors



Applications

- Multi-phase and Vcore regulators
- Voltage Regulator Modules (VRMs) and high power density VRMs
 - Server and desktop
 - Central processing unit (CPU)
 - Graphics processing unit (GPU)
 - Application specific integrated circuit (ASIC)
- Data networking and storage systems
- Graphics cards and battery power systems
- Point-of-Load modules (POL)

Product features

- High current carrying capacity
- Low core loss
- Magnetically shielded
- Inductance Range from 100 nH to 180 nH
- Current range from 60 A to 100 A
- 10.8 mm x 8.2 mm footprint surface mount package in an 8.2 mm height
- Moisture Sensitivity Level: 1
- Ferrite core material

Environmental data

- Storage temperature range (Component): -40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020 (latest revision) compliant
- Halogen free, lead free, RoHS compliant



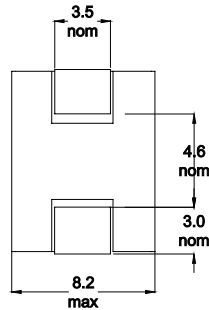
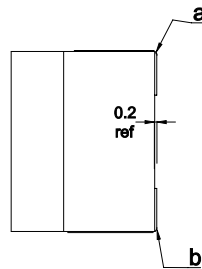
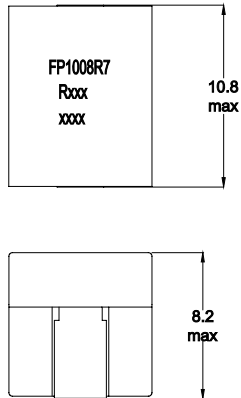
Product specifications

Part Number ⁸	OCL ¹ (nH) ±10%	FLL ² (nH) minimum	I _{rms} ³ (A)	I _{sat} 1 ⁴ (A)	I _{sat} 2 ⁵ (A)	I _{sat} 3 ⁶ (A)	DCR (mΩ) maximum @ 20°C	K-factor ⁷
FP1008R7-R100-R	100	72	72	100	90	84	0.120	361
FP1008R7-R120-R	120	86	72	90	75	70	0.120	361
FP1008R7-R150-R	150	108	72	72	60	56	0.120	361
FP1008R7-R180-R	180	130	72	60	50	46	0.120	361

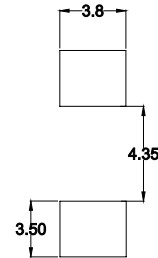
1. Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 0.1 Vrms, 0.0 Adc, +25 °C
2. Full Load Inductance (FLL) Test Parameters: 100 kHz, 0.1 Vrms, I_{sat}1, +25 °C
3. I_{rms}: DC current for an approximate temperature rise of 40 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125 °C under worst case operating conditions verified in the end application.
4. I_{sat}1: Peak current for approximately 20% rolloff @ +25 °C
5. I_{sat}2: Peak current for approximately 20% rolloff @ +100 °C
6. I_{sat}3: Peak current for approximately 20% rolloff @ +125 °C

7. K-factor: Used to determine B_{pp} for core loss (see graph).
 $B_{pp} = K * L * \Delta I * 10^{-3}$, B_{pp}(Gauss), K: (K-factor from table),
 L: (Inductance in nH), ΔI (Peak to peak ripple current in Amps).
8. Part Number Definition: FP1008R7-Rxxx-R
 FP1008R7= Product code and size
 x= Version indicator
 Rxxx= Inductance value in μH, R= decimal point
 -R suffix = RoHS compliant

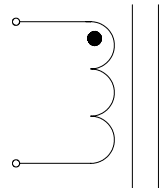
Dimensions (mm)



Recommended Pad Layout



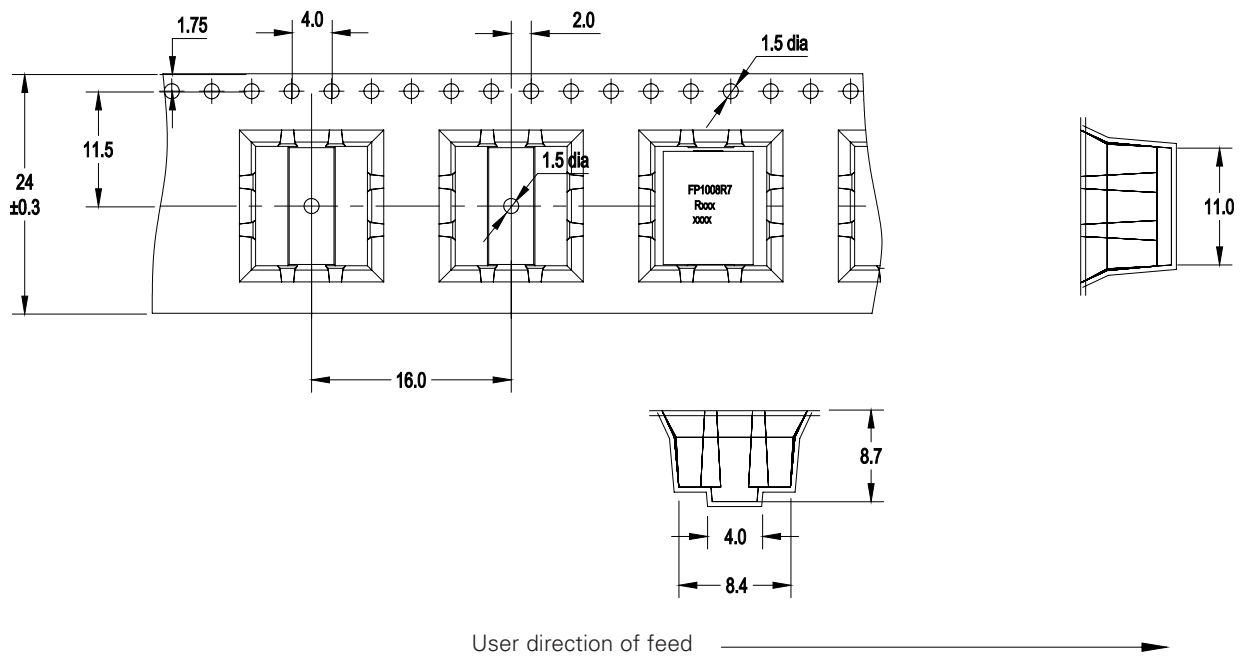
Schematic



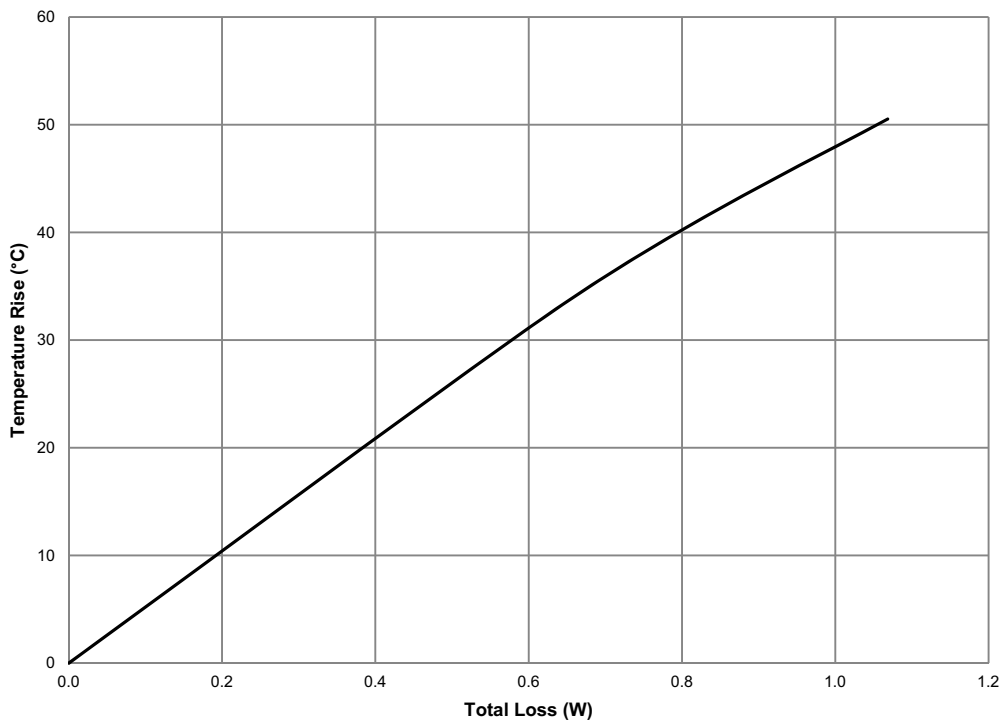
Part marking: FP1008R7, Rxxx (xxx=inductance value in μH, R=decimal point),
 xxxx=Lot code
 Tolerances are ±0.15 millimeters unless stated otherwise.
 All soldering surfaces to be coplanar within 0.1 millimeters
 Pad layout tolerances are ±0.1 millimeters unless stated otherwise
 DCR measured from point "a" to point "b"
 Do not route traces or vias underneath the inductor

Packaging information (mm)

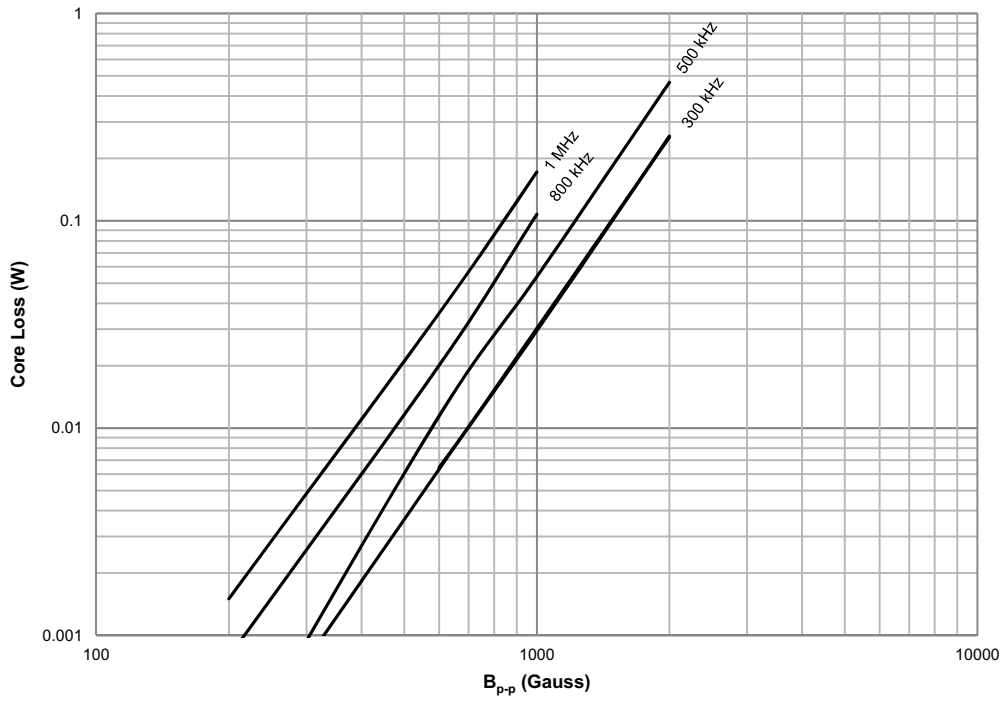
Supplied in tape and reel packaging , 400 parts per 13" diameter reel



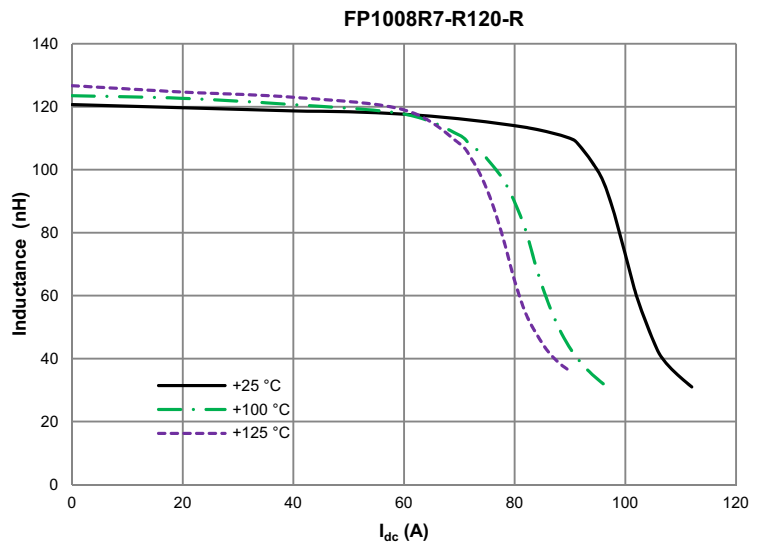
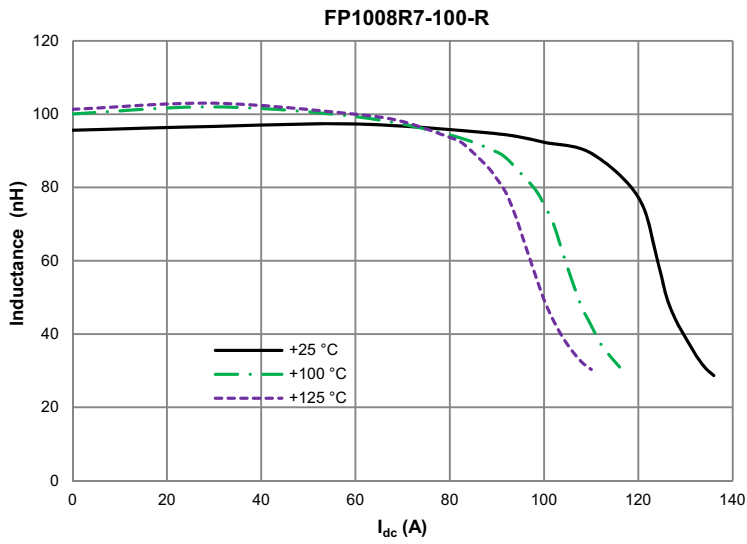
Temperature rise vs. total loss



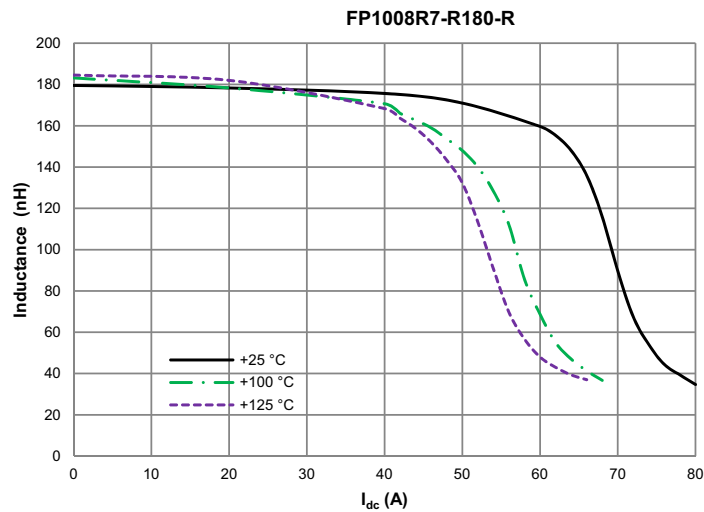
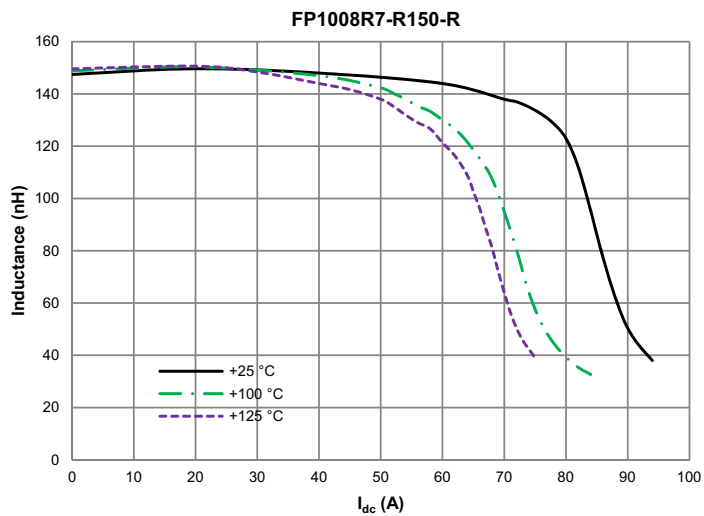
Core loss vs. B_{p-p}



Inductance characteristics



Inductance characteristics



Solder reflow profile

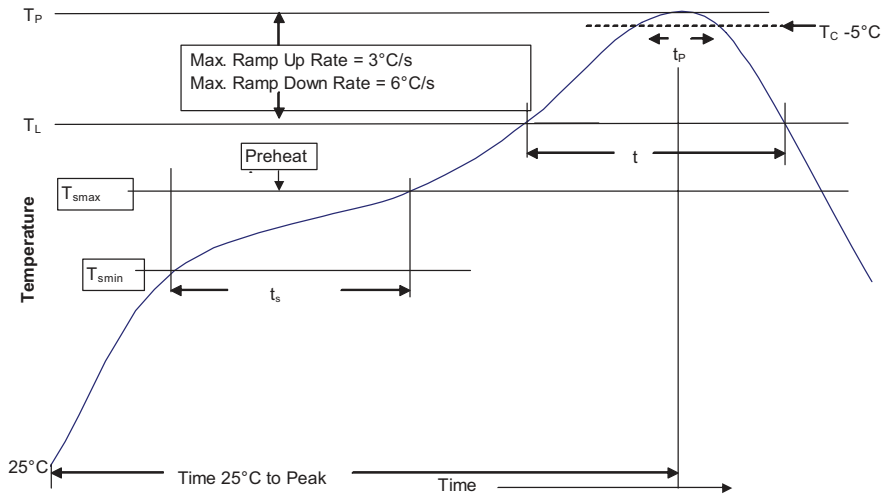


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5mm	235 °C	220 °C
≥2.5mm	220 °C	220 °C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6mm	260 °C	260 °C	260 °C
1.6 – 2.5mm	260 °C	250 °C	245 °C
>2.5mm	250 °C	245 °C	245 °C

Reference JDEC J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T _{smin})	100 °C	150 °C
• Temperature max. (T _{smax})	150 °C	200 °C
• Time (T _{smin} to T _{smax}) (t _s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T _{smax} to T _p	3 °C/ Second Max.	3 °C/ Second Max.
Liquidous temperature (T _L)	183 °C	217 °C
Time at liquidous (t _L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T _p)*	Table 1	Table 2
Time (t _p)** within 5 °C of the specified classification temperature (T _C)	20 Seconds**	30 Seconds**
Average ramp-down rate (T _p to T _{smax})	6 °C/ Second Max.	6 °C/ Second Max.
Time 25 °C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.
** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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